Device Material Content

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Package: 756 caBGA
Total Device Weight 2.483 Grams

Package Code: BG756
Products: FE5

Assembly: ASEM
Size (mm): 27 x 27
Lead pitch (mm): 0.8
MSL: 3
Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.07%	0.0266						Die size: 6.55 x 7.04 mm
			1.07%	0.0266	Silicon chip	7440-21-3	100.00%	
Mold Compound	44.79%	1.1122						Mold Compound: Sumitomo G750SE (ULA)
			3.14%	0.0779	Epoxy Resin	-	7.00%	
			2.24%	0.0556	Phenol Novolac	9003-35-4	5.00%	
			2.24%	0.0556	Metal Hydroxide	-	5.00%	
			0.22%	0.0056	Carbon Black	1333-86-4	0.50%	
			36.95%	0.9176	Silica Fused	60676-86-0	82.50%	
D/A Epoxy	0.16%	0.0040						Die attach epoxy: Henkel (Ablebond) 2100A
			0.13%	0.00318	Silver	7440-22-4	80.00%	
			0.03%	0.00079	Esters & resins	-	20.00%	
Wire	0.20%	0.0050						0.8 mil diameter; 1 wire per solder ball
			0.20%	0.0049	Copper	7440-50-8	98.50%	
			0.00%	0.0001	Palladium	7440-05-3	1.50%	
Solder Balls	7.59%	0.1885						SAC305
			7.32%	0.1819	Tin (Sn)	7440-31-5	96.50%	
			0.23%	0.0057	Silver (Ag)	7440-22-4	3.00%	
			0.04%	0.0009	Copper (Cu)	7440-50-8	0.50%	
Substrate	30.02%	0.7455						BT Resin CCL-HL832NX-A*
			9.61%	0.2386	BT Resins	-	32.00%	
			20.42%	0.5070	Glass fiber	65997-17-3	68.00%	
Foil	11.22%	0.2786						
			9.49%	0.2356	Copper	7440-50-8	84.56%	
			1.65%	0.0409	Nickel	7440-02-0	14.70%	
			0.08%	0.0021	Gold	7440-57-5	0.74%	
Solder Mask	4.95%	0.1228						Solder mask PSR4000 AUS 308
			2.78%	0.0690	Quartz	14808-60-7	56.20%	
			0.79%	0.0197	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
			1.09%	0.0270	Barium Sulfate	7727-43-7	22.00%	
			0.15%	0.0037	Talc (containing no asbestiform fibers)	14807-96-6	3.00%	
			0.14%	0.0034	Trade secret ingredients	-	2.80%	

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Br/Cl/Sb
Pb lead-free
RoHS

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